


Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

 Claim 1 (withdrawn). Method for producing a ceramic body, which has a monolithic multilayer structure and which contains at least one passive electronic module, comprising the method steps:

- a) producing a green film containing a binder,
- b) stacking at least one green film having a ceramic material made of glass ceramic, which becomes compacted at a first temperature interval, and at least one green film having a ceramic material made of glass ceramic, which becomes compacted at a temperature interval, which is different from the first temperature interval, to a stack,
- c) laminating the stack to a composite,
- d) removing binding material from the composite at an increased temperature,
- e) sintering the composite at a temperature of the first temperature interval until the ceramic material, which becomes compacted in this temperature interval, is mainly compacted, and
- f) sintering the composite at a temperature of the temperature interval that is different from the first temperature interval until the ceramic material, which becomes compacted at the temperature interval that is different from the first temperature interval, is mainly compacted.

Claim 2 (withdrawn). Method according to claim 1, whereby the stacking, laminating, removing and/or sintering occurs in a matrix.

Claim 3 (withdrawn). Method according to claim 1, whereby at least one opening is generated in a green film and whereby the opening is filled with an electrically conducting material.

Claim 4 (withdrawn). Method according to claim 3, whereby the opening is generated by punching.

Claim 5 (withdrawn). Method according to claim 3, whereby the opening is filled by means of a screen printing method.

Claim 6 (withdrawn). Method according to claim 1, whereby an electrically conducting material is attached to a surface of a green film and/or the body.

Claim 7 (withdrawn). Method according to claim 6, whereby the electrically conducting material is attached by means of silk screen process printing.

Claim 8 (withdrawn). Method according to claim 1, whereby the stack is sintered onto a metal body.

Claim 9 (canceled).

Claim 10 (currently amended). A ceramic body having a monolithic multilayer structure, comprising:

at least one passive electronic module;

at least one layer comprising a first ceramic material made of glass ceramic, which becomes compacted in a first temperature interval; and

at least one layer comprising a second ceramic material made of glass ceramic, which becomes compacted at a temperature interval that is different from the first temperature interval; and

at least one layer comprising a metal foil to form an electrical conductor ~~The body according to claim 9,~~ wherein the ceramic materials exhibit an essentially identical coefficient of expansion of between 6 and 7 ppm/K at a specific temperature range.

Claim 11 (currently amended). The body according to claim 10 9, which includes a layer stack having a layer sequence in a direction, and a layer stack having the same layer sequence in opposite direction, are arranged on top of one another.

Claim 12. (currently amended). The body according to claim 10 9, wherein the second ceramic material becomes compacted at the temperature interval between 720°C and 850°C.

Claim 13 (previously presented). The body according to claim 12, wherein the second ceramic material becomes compacted at the temperature interval between 870°C and 970°C.

Claim 14. (currently amended). The body according to claim 10 9, wherein the body comprises at least one layer composed of an electrode material.

Claim 15. (previously presented). The body according to claim 14, wherein the body is arranged on a metal body.

Claim 16 (previously presented). The body according to claim 15, wherein the at least one passive electronic module, the layer comprising an electrode material and/or the metal body comprises at least one material, which is selected from the group gold, copper, molybdenum, palladium, platinum, silver and/or wolfram.

Claim 17 (canceled).

E/ Claim 18 (previously presented). The body according to claim 14, wherein the layer comprising an electrode material comprises at least one material, which is selected from the group consisting of gold, copper molybdenum, palladium, platinum, silver and tungsten.

Claim 19. (currently amended). The body according to claim 10 9, wherein one of the ceramic materials becomes compacted at the temperature interval between 870°C and 970°C.

Claim 20. (currently amended). The body according to claim 10 9, which is a substance for a high-frequency module.
